Lattice Semiconductor Corporation - LFXP10E-5FN388C Datasheet

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

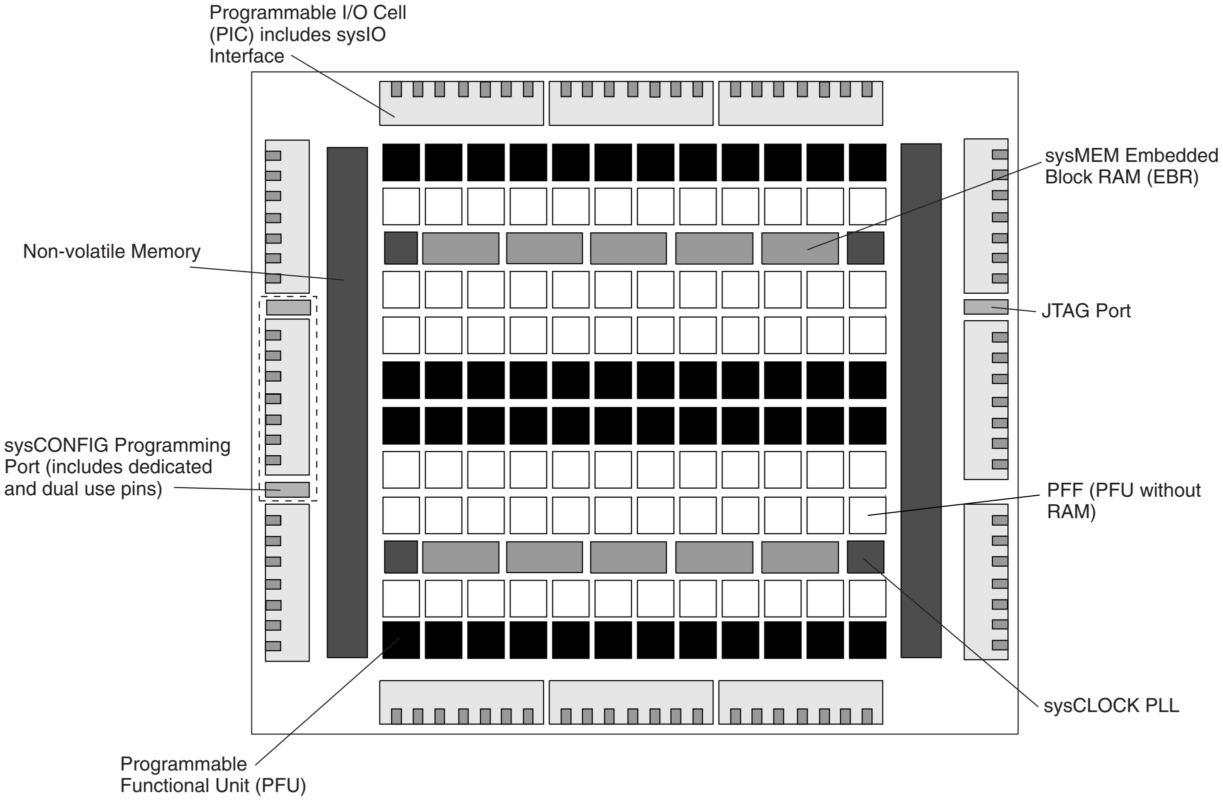
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	10000
Total RAM Bits	221184
Number of I/O	244
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp10e-5fn388c

Figure 2-1. LatticeXP Top Level Block Diagram



PFU and PFF Blocks

The core of the LatticeXP devices consists of PFU and PFF blocks. The PFUs can be programmed to perform Logic, Arithmetic, Distributed RAM and Distributed ROM functions. PFF blocks can be programmed to perform Logic, Arithmetic and ROM functions. Except where necessary, the remainder of the data sheet will use the term PFU to refer to both PFU and PFF blocks.

Each PFU block consists of four interconnected slices, numbered 0-3 as shown in Figure 2-2. All the interconnections to and from PFU blocks are from routing. There are 53 inputs and 25 outputs associated with each PFU block.

Figure 2-2. PFU Diagram

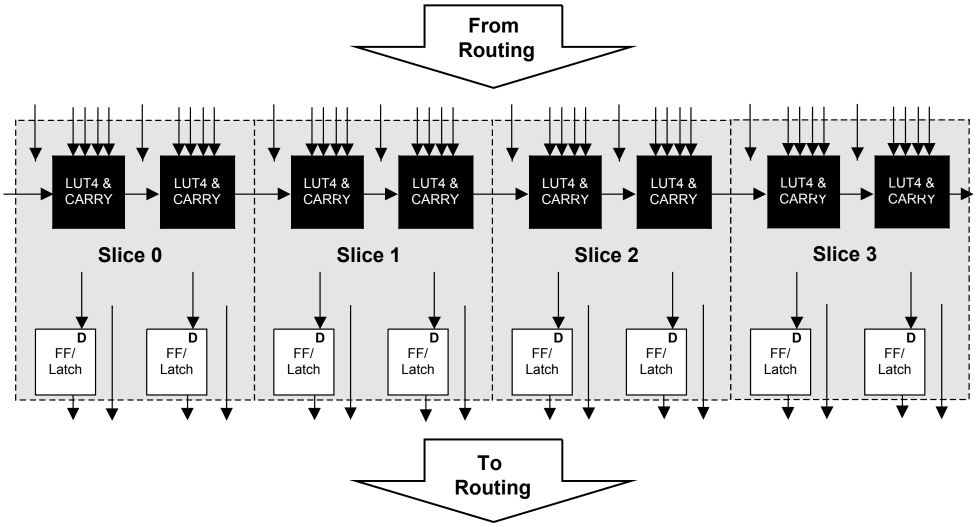
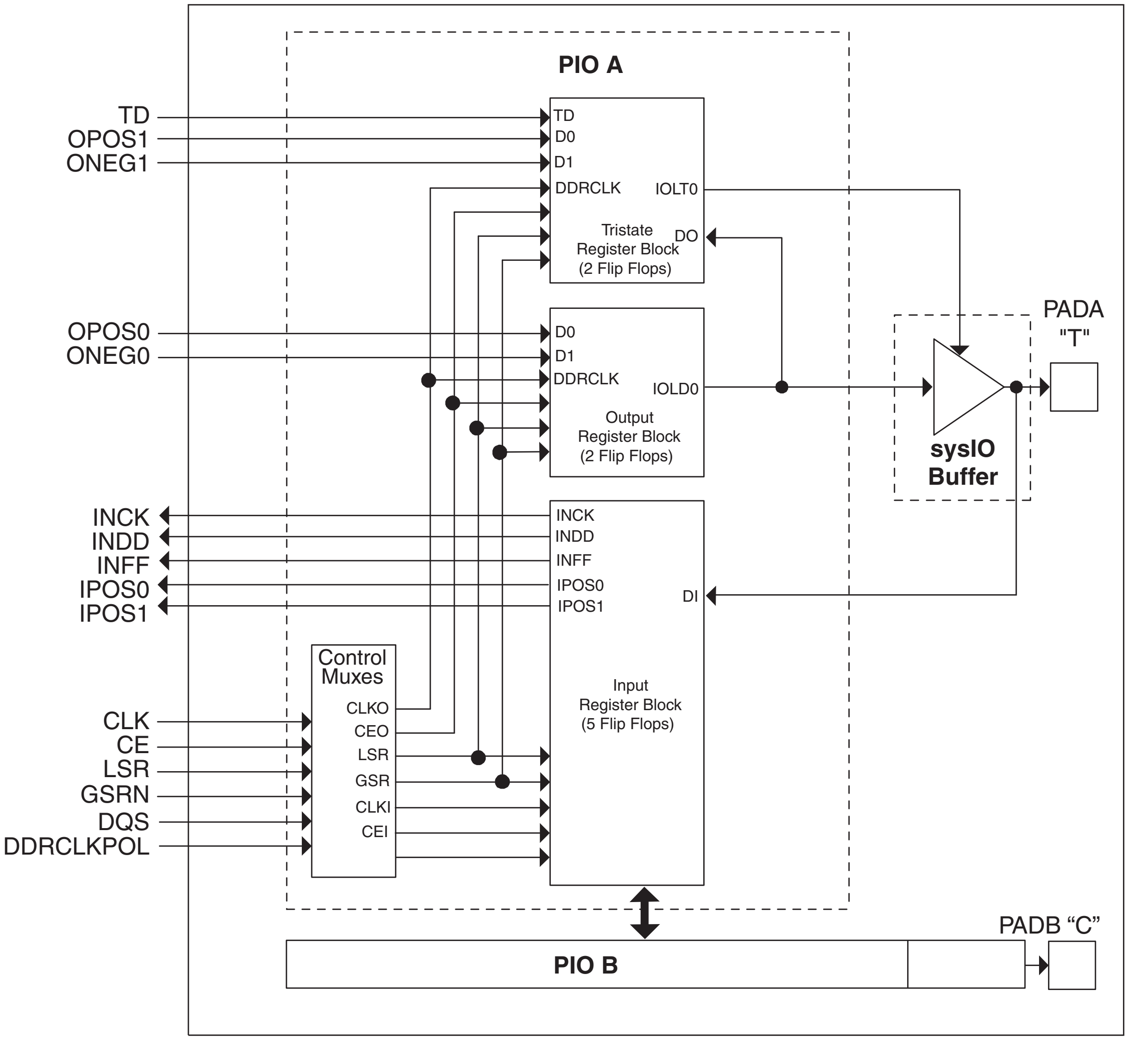


Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Figure 2-21. Input Register DDR Waveforms

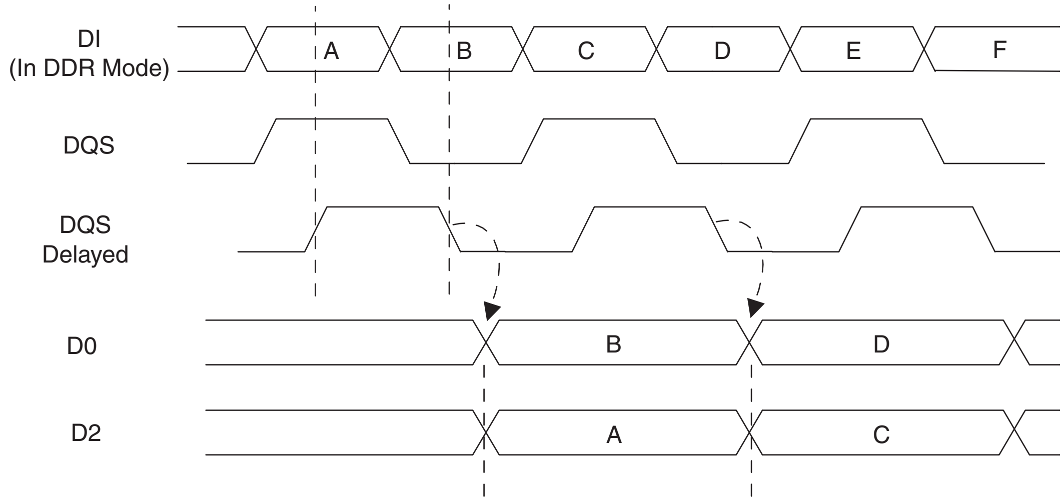
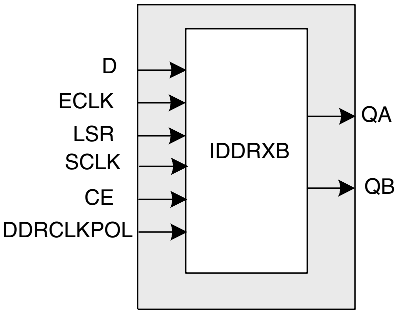


Figure 2-22. INDDRXB Primitive



Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-23 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or as a latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-24 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Figure 2-26. DQS Local Bus

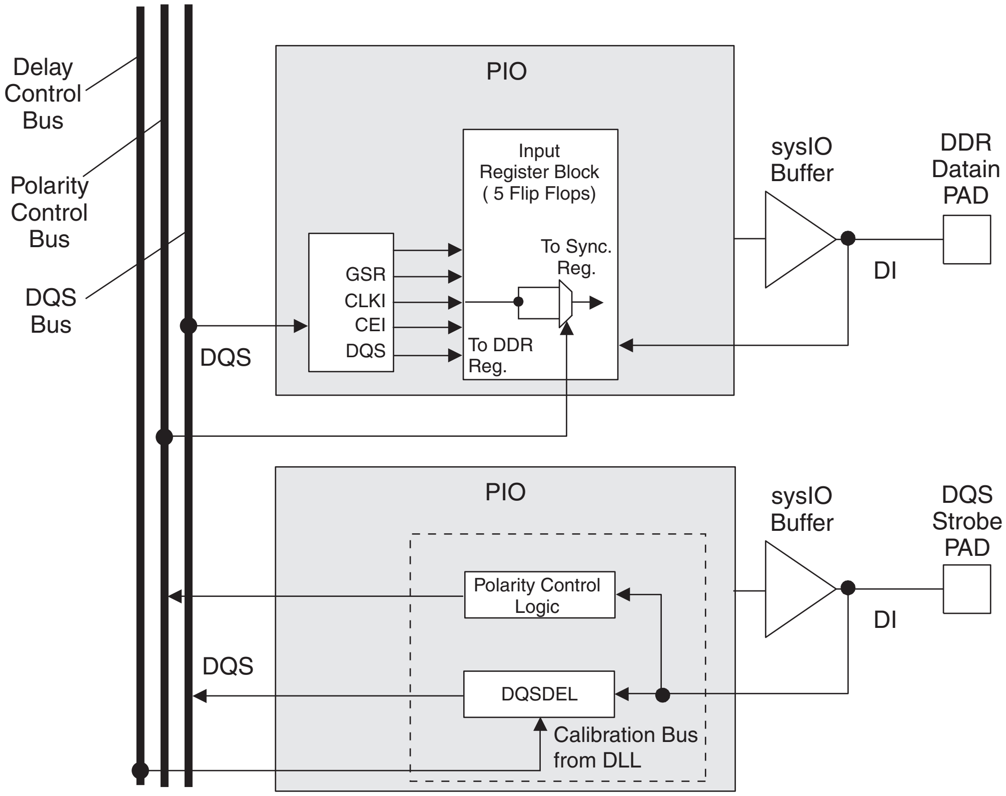
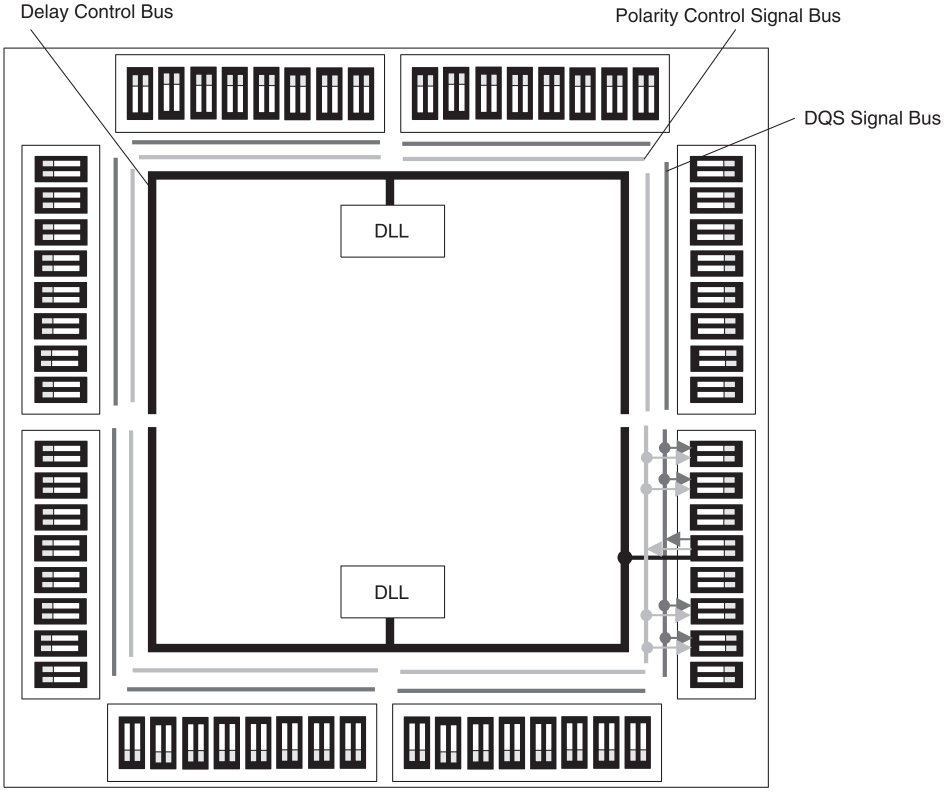


Figure 2-27. DLL Calibration Bus and DQS/DQS Transition Distribution



Lattice Semiconductor Corporation

LatticeXP Family Data Sheet DC and Switching Characteristics

November 2007 **Data Sheet DS1001**

Absolute Maximum Ratings[1, 2, 3, 4]

	XPE (1.2V)	XPC (1.8V/2.5V/3.3V)
Supply Voltage V_{CC}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCP}	-0.5 to 1.32V	-0.5 to 3.75V
Supply Voltage V_{CCAUX}	-0.5 to 3.75V	-0.5 to 3.75V
Supply Voltage V_{CCJ}	-0.5 to 3.75V	-0.5 to 3.75V
Output Supply Voltage V_{CCIO}	-0.5 to 3.75V	-0.5 to 3.75V
I/O Tristate Voltage Applied[5]	-0.5 to 3.75V	-0.5 to 3.75V
Dedicated Input Voltage Applied [5]	-0.5 to 3.75V	-0.5 to 4.25V
Storage Temperature (Ambient)	-65 to 150°C	-65 to 150°C
Junction Temp. (Tj)	+125°C	+125°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions outside of those indicated in the operational sections of this specification is not implied.
2. Compliance with the Lattice *Thermal Management* document is required.
3. All voltages referenced to GND.
4. All chip grounds are connected together to a common package GND plane.
5. Overshoot and undershoot of -2V to (V_{IHMAX} + 2) volts is permitted for a duration of <20ns.

Recommended Operating Conditions[3]

Symbol	Parameter	Min.	Max.	Units
V_{CC}	Core Supply Voltage for 1.2V Devices	1.14	1.26	V
	Core Supply Voltage for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCP}	Supply Voltage for PLL for 1.2V Devices	1.14	1.26	V
	Supply Voltage for PLL for 1.8V/2.5V/3.3V Devices	1.71	3.465	V
V_{CCAUX}[4]	Auxiliary Supply Voltage	3.135	3.465	V
V_{CCIO}[1, 2]	I/O Driver Supply Voltage	1.14	3.465	V
V_{CCJ}[1]	Supply Voltage for IEEE 1149.1 Test Access Port	1.14	3.465	V
t_{JCOM}	Junction Temperature, Commercial Operation	0	85	C
t_{JIND}	Junction Temperature, Industrial Operation	-40	100	C
$t_{JFLASHCOM}$	Junction Temperature, Flash Programming, Commercial	0	85	C
$t_{JFLASHIND}$	Junction Temperature, Flash Programming, Industrial	0	85	C

1. If V_{CCIO} or V_{CCJ} is set to 3.3V, they must be connected to the same power supply as V_{CCAUX}. For the XPE devices (1.2V V_{CC}), if V_{CCIO} or V_{CCJ} is set to 1.2V, they must be connected to the same power supply as V_{CC}.
2. See recommended voltages by I/O standard in subsequent table.
3. The system designer must ensure that the FPGA design stays within the specified junction temperature and package thermal capabilities of the device based on the expected operating frequency, activity factor and environment conditions of the system.
4. V_{CCAUX} ramp rate must not exceed 30mV/µs during power up when transitioning between 0V and 3.3V.

Initialization Supply Current[1, 2, 3, 4, 5, 6]

Over Recommended Operating Conditions

Symbol	Parameter	Device	Typ.[7]	Units
I_{CC}	Core Power Supply	LFXP3E	40	mA
		LFXP6E	50	mA
		LFXP10E	110	mA
		LFXP15E	140	mA
		LFXP20E	250	mA
		LFXP3C	60	mA
		LFXP6C	70	mA
		LFXP10C	150	mA
		LFXP15C	180	mA
		LFXP20C	290	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15 /C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply	All	2	mA

1. Until DONE signal is active.
2. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
3. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
4. Frequency 0MHz.
5. Typical user pattern.
6. Assume normal bypass capacitor/decoupling capacitor across the supply.
7. T_A=25°C, power supplies at nominal voltage.

Programming and Erase Flash Supply Current[1, 2, 3, 4, 5]

Symbol	Parameter	Device	Typ.[6]	Units
I_{CC}	Core Power Supply	LFXP3E	30	mA
		LFXP6E	40	mA
		LFXP10E	50	mA
		LFXP15E	60	mA
		LFXP20E	70	mA
		LFXP3C	50	mA
		LFXP6C	60	mA
		LFXP10C	90	mA
		LFXP15C	100	mA
		LFXP20C	110	mA
I_{CCAUX}	Auxiliary Power Supply V_{CCAUX} = 3.3V	LFXP3E/C	50	mA
		LFXP6E/C	60	mA
		LFXP10E/C	90	mA
		LFXP15E/C	110	mA
		LFXP20E/C	130	mA
I_{CCJ}	V_{CCJ} Power Supply[7]	All	2	mA

1. For further information on supply current, please see details of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V_{CCIO} or GND.
3. Blank user pattern; typical Flash pattern.
4. Bypass or decoupling capacitor across the supply.
5. JTAG programming is at 1MHz.
6. T_A=25°C, power supplies at nominal voltage.
7. When programming via JTAG.

LVPECL

The LatticeXP devices support differential LVPECL standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The LVPECL input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-3 is one possible solution for point-to-point signals.

Figure 3-3. Differential LVPECL

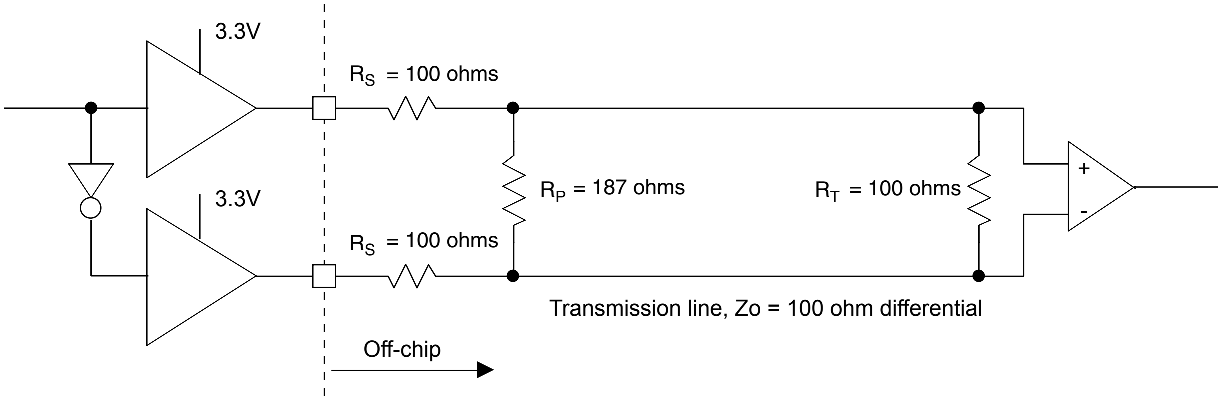


Table 3-3. LVPECL DC Conditions[1]

Over Recommended Operating Conditions

Symbol	Description	Typical	Units
Z_{OUT}	Output impedance	100	ohms
R_P	Driver parallel resistor	187	ohms
R_S	Driver series resistor	100	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	2.03	V
V_{OL}	Output low voltage	1.27	V
V_{OD}	Output differential voltage	0.76	V
V_{CM}	Output common mode voltage	1.65	V
Z_{BACK}	Back impedance	85.7	ohms
I_{DC}	DC output current	12.7	mA

1. For input buffer, see LVDS table.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The LatticeXP devices support differential RSDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The RSDS input standard is supported by the LVDS differential input buffer. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LatticeXP Family Timing Adders[1]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.5	0.5	0.5	ns
LVDS25	LVDS	0.4	0.4	0.4	ns
BLVDS25	BLVDS	0.5	0.5	0.5	ns
LVPECL33	LVPECL	0.6	0.6	0.6	ns
HSTL18_I	HSTL_18 class I	0.4	0.4	0.4	ns
HSTL18_II	HSTL_18 class II	0.4	0.4	0.4	ns
HSTL18_III	HSTL_18 class III	0.4	0.4	0.4	ns
HSTL18D_I	Differential HSTL 18 class I	0.4	0.4	0.4	ns
HSTL18D_II	Differential HSTL 18 class II	0.4	0.4	0.4	ns
HSTL18D_III	Differential HSTL 18 class III	0.4	0.4	0.4	ns
HSTL15_I	HSTL_15 class I	0.5	0.5	0.5	ns
HSTL15_III	HSTL_15 class III	0.5	0.5	0.5	ns
HSTL15D_I	Differential HSTL 15 class I	0.5	0.5	0.5	ns
HSTL15D_III	Differential HSTL 15 class III	0.5	0.5	0.5	ns
SSTL33_I	SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33_II	SSTL_3 class II	0.6	0.6	0.6	ns
SSTL33D_I	Differential SSTL_3 class I	0.6	0.6	0.6	ns
SSTL33D_II	Differential SSTL_3 class II	0.6	0.6	0.6	ns
SSTL25_I	SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25_II	SSTL_2 class II	0.5	0.5	0.5	ns
SSTL25D_I	Differential SSTL_2 class I	0.5	0.5	0.5	ns
SSTL25D_II	Differential SSTL_2 class II	0.5	0.5	0.5	ns
SSTL18_I	SSTL_18 class I	0.5	0.5	0.5	ns
SSTL18D_I	Differential SSTL_18 class I	0.5	0.5	0.5	ns
LVTTL33	LVTTL	0.2	0.2	0.2	ns
LVCMOS33	LVCMOS 3.3	0.2	0.2	0.2	ns
LVCMOS25	LVCMOS 2.5	0.0	0.0	0.0	ns
LVCMOS18	LVCMOS 1.8	0.1	0.1	0.1	ns
LVCMOS15	LVCMOS 1.5	0.1	0.1	0.1	ns
LVCMOS12	LVCMOS 1.2	0.1	0.1	0.1	ns
PCI33	PCI	0.2	0.2	0.2	ns
Output Adjusters					
LVDS25E	LVDS 2.5 Emulated	0.3	0.3	0.3	ns
LVDS25	LVDS 2.5	0.3	0.3	0.3	ns
BLVDS25	BLVDS 2.5	0.3	0.3	0.3	ns
LVPECL33	LVPECL 3.3	0.1	0.1	0.1	ns
HSTL18_I	HSTL_18 class I	0.1	0.1	0.1	ns
HSTL18_II	HSTL_18 class II	0.1	0.1	0.1	ns
HSTL18_III	HSTL_18 class III	0.2	0.2	0.2	ns
HSTL18D_I	Differential HSTL 18 class I	0.1	0.1	0.1	ns
HSTL18D_II	Differential HSTL 18 class II	-0.1	-0.1	-0.1	ns
HSTL18D_III	Differential HSTL 18 class III	0.2	0.2	0.2	ns

Flash Download Time

Symbol	Parameter		Min.	Typ.	Max.	Units
$t_{REFRESH}$	PROGRAMN Low-to-High. Transition to Done High.	LFXP3	—	1.1	1.7	ms
		LFXP6	—	1.4	2.0	ms
		LFXP10	—	0.9	1.5	ms
		LFXP15	—	1.1	1.7	ms
		LFXP20	—	1.3	1.9	ms

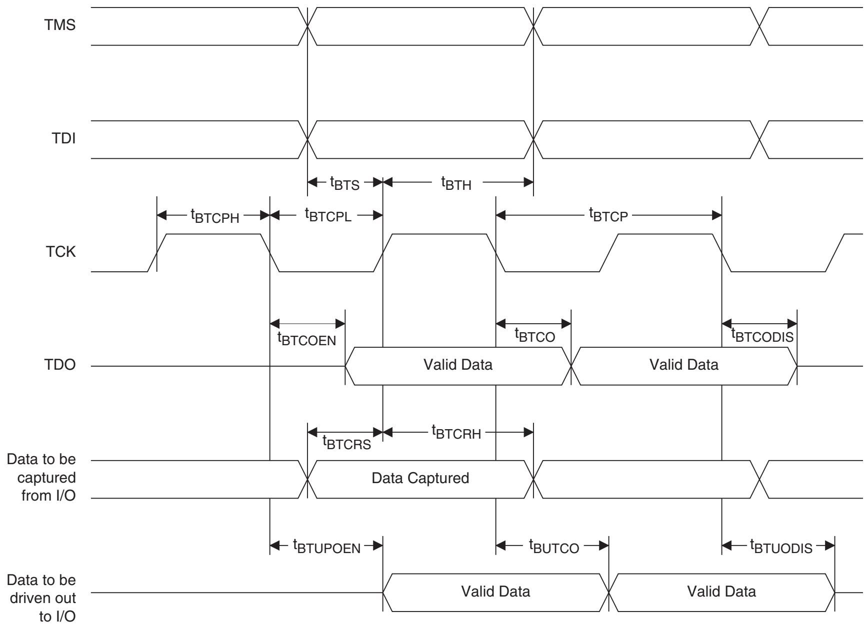
JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
f_{MAX}		—	25	MHz
t_{BTCP}	TCK [BSCAN] clock pulse width	40	—	ns
t_{BTCPH}	TCK [BSCAN] clock pulse width high	20	—	ns
t_{BTCPL}	TCK [BSCAN] clock pulse width low	20	—	ns
t_{BTS}	TCK [BSCAN] setup time	10	—	ns
t_{BTH}	TCK [BSCAN] hold time	8	—	ns
t_{BTRF}	TCK [BSCAN] rise/fall time	50	—	ns
t_{BTCO}	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTCODIS}$	TAP controller falling edge of clock to valid disable	—	10	ns
t_{BTCOEN}	TAP controller falling edge of clock to valid enable	—	10	ns
t_{BTCRS}	BSCAN test capture register setup time	8	—	ns
t_{BTCRH}	BSCAN test capture register hold time	25	—	ns
t_{BUTCO}	BSCAN test update register, falling edge of clock to valid output	—	25	ns
$t_{BTUODIS}$	BSCAN test update register, falling edge of clock to valid disable	—	25	ns
$t_{BTUPOEN}$	BSCAN test update register, falling edge of clock to valid enable	—	25	ns

Timing v.F0.11

Figure 3-12. JTAG Port Timing Waveforms



Pin Information Summary[1]

Pin Type		XP3			XP6		
		100 TQFP	144 TQFP	208 PQFP	144 TQFP	208 PQFP	256 fpBGA
Single Ended User I/O		62	100	136	100	142	188
Differential Pair User I/O[2]		19	35	56	35	58	80
Configuration	Dedicated	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14
TAP		5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6
V_{CC}		2	4	8	4	8	8
V_{CCAUX}		2	2	2	2	2	4
V_{CCPLL}		2	2	2	2	2	2
V_{CCIO}	Bank0	1	1	2	1	2	2
	Bank1	1	1	2	1	2	2
	Bank2	1	1	2	1	2	2
	Bank3	1	1	2	1	2	2
	Bank4	1	2	2	2	2	2
	Bank5	1	1	2	1	2	2
	Bank6	1	1	2	1	2	2
	Bank7	1	1	2	1	2	2
GND		10	13	24	13	24	24
GND_{PLL}		2	2	2	2	2	2
NC		0	0	6	0	0	0
Single Ended/Differential I/O per Bank[2]	Bank0	8/2	12/3	20/8	12/3	20/8	26/11
	Bank1	9/0	12/2	18/6	12/2	18/6	26/11
	Bank2	8/3	12/5	14/6	12/5	17/7	21/9
	Bank3	6/2	13/5	14/6	13/5	14/6	21/9
	Bank4	5/2	14/6	21/9	14/6	21/9	26/11
	Bank5	12/4	12/4	21/9	12/4	21/9	26/11
	Bank6	4/2	13/5	14/6	13/5	17/7	21/9
	Bank7	10/4	12/5	14/6	12/5	14/6	21/9
V_{CCJ}		1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F15	PR10B	2	-	-	PR10B	2	-	-
E15	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
F14	PR8B	2	C[3]	-	PR8B	2	C[3]	-
E14	PR8A	2	T[3]	-	PR8A	2	T[3]	-
D15	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
C15	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
-	GNDIO2	2	-	-	GNDIO2	2	-	-
E16	TDO	-	-	-	TDO	-	-	-
D16	VCCJ	-	-	-	VCCJ	-	-	-
D14	TDI	-	-	-	TDI	-	-	-
C14	TMS	-	-	-	TMS	-	-	-
B14	TCK	-	-	-	TCK	-	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-
A15	PT40B	1	C	-	PT44B	1	C	-
B15	PT40A	1	T	-	PT44A	1	T	-
D12	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C11	PT39A	1	T	DQS	PT43A	1	T	DQS
A14	PT38B	1	-	-	PT42B	1	-	-
B13	PT37A	1	-	-	PT41A	1	-	-
F12	PT36B	1	C	-	PT40B	1	C	-
E11	PT36A	1	T	-	PT40A	1	T	-
A13	PT35B	1	C	-	PT39B	1	C	-
C13	PT35A	1	T	D0	PT39A	1	T	D0
C10	PT34B	1	C	D1	PT38B	1	C	D1
E10	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
A12	PT33B	1	C	-	PT37B	1	C	-
B12	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-
C12	PT32B	1	C	D3	PT36B	1	C	D3
A11	PT32A	1	T	-	PT36A	1	T	-
B11	PT31B	1	C	-	PT35B	1	C	-
D11	PT31A	1	T	DQS	PT35A	1	T	DQS
B9	PT30B	1	-	-	PT34B	1	-	-
D9	PT29A	1	-	D4	PT33A	1	-	D4
A10	PT28B	1	C	-	PT32B	1	C	-
B10	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-
D10	PT27B	1	C	D6	PT31B	1	C	D6

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
AA20	PB36B	4	C	-	PB41B	4	C	-	PB45B	4	C	-
AB21	PB37A	4	T	-	PB42A	4	T	-	PB46A	4	T	-
AA21	PB37B	4	C	-	PB42B	4	C	-	PB46B	4	C	-
AA22	PB38A	4	T	-	PB43A	4	T	-	PB47A	4	T	-
Y21	PB38B	4	C	-	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
W16	PB39A	4	-	-	PB44A	4	T	-	PB48A	4	T	-
W17	-	-	-	-	PB44B	4	C	-	PB48B	4	C	-
Y15	-	-	-	-	PB45A	4	-	-	PB49A	4	-	-
Y16	-	-	-	-	PB46B	4	-	-	PB50B	4	-	-
W19	-	-	-	-	PB47A	4	T	DQS	PB51A	4	T	DQS
W18	-	-	-	-	PB47B	4	C	-	PB51B	4	C	-
W20	-	-	-	-	PB48A	4	-	-	PB52A	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-	GNDIO4	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
T20	PR35B	3	C[3]	-	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T19	PR35A	3	T[3]	-	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
U19	PR34B	3	C	RLM0_PLLC_FB_A	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
U20	PR34A	3	T	RLM0_PLLT_FB_A	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
V19	PR33B	3	C[3]	-	PR37B	3	C[3]	-	PR41B	3	C[3]	-
V20	PR33A	3	T[3]	DQS	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
R19	PR32B	3	-	-	PR36B	3	-	-	PR40B	3	-	-
R20	PR31A	3	-	VREF1_3	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
W21	PR30B	3	C[3]	-	PR34B	3	C[3]	-	PR38B	3	C[3]	-
Y22	PR30A	3	T[3]	-	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
P19	PR29B	3	C	-	PR33B	3	C	-	PR37B	3	C	-
P20	PR29A	3	T	-	PR33A	3	T	-	PR37A	3	T	-
V21	PR28B	3	C[3]	-	PR32B	3	C[3]	-	PR36B	3	C[3]	-
W22	PR28A	3	T[3]	-	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U21	PR26B	3	C[3]	-	PR30B	3	C[3]	-	PR34B	3	C[3]	-
V22	PR26A	3	T[3]	-	PR30A	3	T[3]	-	PR34A	3	T[3]	-
T21	PR25B	3	C	RLM0_PLLC_IN_A	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
U22	PR25A	3	T	RLM0_PLLT_IN_A	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
R21	PR24B	3	C[3]	-	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T22	PR24A	3	T[3]	DQS	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
N19	PR23B	3	-	-	PR27B	3	-	-	PR31B	3	-	-
N20	PR22A	3	-	VREF2_3	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
R22	PR21B	3	C[3]	-	PR25B	3	C[3]	-	PR29B	3	C[3]	-
P22	PR21A	3	T[3]	-	PR25A	3	T[3]	-	PR29A	3	T[3]	-
P21	PR20B	3	C	-	PR24B	3	C	-	PR28B	3	C	-
N21	PR20A	3	T	-	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-	GNDIO3	3	-	-
M20	PR19B	3	C[3]	-	PR23B	3	C[3]	-	PR27B	3	C[3]	-
M19	PR19A	3	T[3]	-	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	GNDP1	-	-	-	GNDP1	-	-	-	GNDP1	-	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
A7	PT13A	0	T	DI	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT12B	0	C	-	PT17B	0	C	-	PT21B	0	C	-
C6	PT12A	0	T	CSN	PT17A	0	T	CSN	PT21A	0	T	CSN
C10	PT11B	0	C	-	PT16B	0	C	-	PT20B	0	C	-
C9	PT11A	0	T	-	PT16A	0	T	-	PT20A	0	T	-
A6	PT10B	0	C	VREF2_0	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
B6	PT10A	0	T	DQS	PT15A	0	T	DQS	PT19A	0	T	DQS
A5	PT9B	0	-	-	PT14B	0	-	-	PT18B	0	-	-
B5	PT8A	0	-	-	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT7B	0	C	-	PT12B	0	C	-	PT16B	0	C	-
A4	PT7A	0	T	-	PT12A	0	T	-	PT16A	0	T	-
D9	PT6B	0	C	-	PT11B	0	C	-	PT15B	0	C	-
D8	PT6A	0	T	-	PT11A	0	T	-	PT15A	0	T	-
B4	PT5B	0	C	-	PT10B	0	C	-	PT14B	0	C	-
A2	PT5A	0	T	-	PT10A	0	T	-	PT14A	0	T	-
A3	PT4B	0	C	-	PT9B	0	C	-	PT13B	0	C	-
B3	PT4A	0	T	-	PT9A	0	T	-	PT13A	0	T	-
C4	PT3B	0	C	-	PT8B	0	C	-	PT12B	0	C	-
C3	PT3A	0	T	-	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C2	-	-	-	-	PT7B	0	C	-	PT11B	0	C	-
D3	PT2A	0	-	-	PT7A	0	T	DQS	PT11A	0	T	DQS
D7	-	-	-	-	PT6B	0	-	-	PT10B	0	-	-
D6	-	-	-	-	PT5A	0	-	-	PT9A	0	-	-
E4	-	-	-	-	PT4B	0	C	-	PT8B	0	C	-
D4	-	-	-	-	PT4A	0	T	-	PT8A	0	T	-
D5	-	-	-	-	PT3B	0	-	-	PT7B	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C1	CFG0	0	-	-	CFG0	0	-	-	CFG0	0	-	-
B2	CFG1	0	-	-	CFG1	0	-	-	CFG1	0	-	-
B1	DONE	0	-	-	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-	GND	-	-	-
H11	GND	-	-	-	GND	-	-	-	GND	-	-	-
H12	GND	-	-	-	GND	-	-	-	GND	-	-	-
H13	GND	-	-	-	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-	GND	-	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
H13	VCCIO1	1	-	-	VCCIO1	1	-	-
K15	VCCIO2	2	-	-	VCCIO2	2	-	-
L15	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-
L17	VCCIO2	2	-	-	VCCIO2	2	-	-
M15	VCCIO3	3	-	-	VCCIO3	3	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-
M17	VCCIO3	3	-	-	VCCIO3	3	-	-
N15	VCCIO3	3	-	-	VCCIO3	3	-	-
R12	VCCIO4	4	-	-	VCCIO4	4	-	-
R13	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-
U12	VCCIO4	4	-	-	VCCIO4	4	-	-
R10	VCCIO5	5	-	-	VCCIO5	5	-	-
R11	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-
U11	VCCIO5	5	-	-	VCCIO5	5	-	-
M6	VCCIO6	6	-	-	VCCIO6	6	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-
M8	VCCIO6	6	-	-	VCCIO6	6	-	-
N8	VCCIO6	6	-	-	VCCIO6	6	-	-
K8	VCCIO7	7	-	-	VCCIO7	7	-	-
L6	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-
L8	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

Lattice Semiconductor Corporation

LatticeXP Family Data Sheet
Ordering Information

December 2005 **Data Sheet DS1001**

Part Number Description

LFXP XX X – X XXXXXX X

Device Family
LatticeXP FPGA

Logic Capacity
3K LUTs = 3
6K LUTs = 6
10K LUTs = 10
15K LUTs = 15
20K LUTs = 20

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked per table below.

Grade
C = Commercial
I = Industrial

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F388 = 388-ball fpBGA
F484 = 484-ball fpBGA

TN100 = 100-pin Lead-free TQFP
TN144 = 144-pin Lead-free TQFP
QN208 = 208-pin Lead-free PQFP
FN256 = 256-ball Lead-free fpBGA
FN388 = 388-ball Lead-free fpBGA
FN484 = 484-ball Lead-free fpBGA

Speed
3 = Slowest
4
5 = Fastest

Ordering Information (Contact Factory for Specific Device Availability)

Note:þLatticeXP devices are dual marked. For example, the commercial speed grade LFXP10E-4F256C is also marked with industrial grade -3I (LFXP10E-3F256I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484C	300	1.8/2.5/3.3V	-3	fpBGA	484	COM	15.5K
LFXP15C-4F484C	300	1.8/2.5/3.3V	-4	fpBGA	484	COM	15.5K
LFXP15C-5F484C	300	1.8/2.5/3.3V	-5	fpBGA	484	COM	15.5K
LFXP15C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	15.5K
LFXP15C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	15.5K
LFXP15C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	15.5K
LFXP15C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	15.5K
LFXP15C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	15.5K
LFXP15C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4F484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5F484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4Q208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5Q208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3T144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4T144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5T144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3T100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4T100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5T100C	62	1.2V	-5	TQFP	100	COM	3.1K

LatticeXP Family Data Sheet Supplemental Information

November 2007 | Data Sheet DS1001

For Further Information

A variety of technical notes for the LatticeXP family are available on the Lattice website at www.latticesemi.com.

- LatticeECP/EC and LatticeXP sysIO Usage Guide (TN1056)
- Lattice ispTRACY Usage Guide (TN1054)
- LatticeECP/EC and LatticeXP sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC and LatticeXP Devices (TN1051)
- LatticeECP/EC and XP DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeXP sysCONFIG Usage Guide (TN1082)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com